

Darlington Complementary Silicon Power Transistors BDX33B, BDX33C (NPN) BDX34B, BDX34C (PNP)

These devices are designed for general purpose and low speed switching applications.

Features

- High DC Current Gain $h_{FE} = 2500$ (typ.) at $I_C = 4.0$
- Collector-Emitter Sustaining Voltage at 100 mAdc

• Low Collector-Emitter Saturation Voltage

$$V_{CE(sat)} = 2.5 \text{ Vdc (max) at } I_C = 3.0 \text{ Adc}$$

- BDX33B, 33C/34B, 34C

- Monolithic Construction with Build-In Base-Emitter Shunt Resistors
- These Devices are Pb-Free and are RoHS Compliant*

MAXIMUM RATINGS

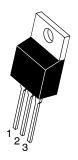
Rating	Symbol	Value	Unit
Collector–Emitter Voltage BDX33B, BDX34B BDX33C, BDX34C	V _{CEO}	80 100	Vdc
Collector-Base Voltage BDX33B, BDX34B BDX33C, BDX34C	V _{CB}	80 100	Vdc
Emitter-Base Voltage	V _{EB}	5.0	Vdc
Collector Current Continuous Peak	I _C	10 15	Adc
Base Current	Ι _Β	0.25	Adc
Total Device Dissipation @ T _C = 25°C Derate above 25°C	P _D	70 0.56	W W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

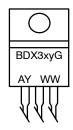
Characteristics	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.78	°C/W

DARLINGTON 10 AMPERE COMPLEMENTARY SILICON POWER TRANSISTORS 80-100 VOLTS, 65 WATTS



TO-220 CASE 221A STYLE 1

MARKING DIAGRAM



BDX3xy = Device Code x = 3 or 4y = B or C

Assembly Location

Year WW Work Week Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 5.

1

^{*}For additional information on our Pb-Free strategy and soldering details, please download the **onsem**i Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

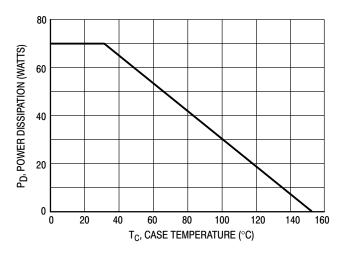


Figure 1. Power Derating

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit		
OFF CHARACTERISTICS						
Collector–Emitter Sustaining Voltage (Note 1) $(I_C = 100 \text{ mAdc}, I_B = 0)$	BDX33B/BDX34B BDX33C/BDX34C	V _{CEO(sus)}	80 100	- -	Vdc	
Collector–Emitter Sustaining Voltage (Note 1) $(I_C = 100 \text{ mAdc}, I_B = 0, R_{BE} = 100)$	BDX33B/BDX34B BDX33C/BDX33C	V _{CER(sus)}	80 100	- -	Vdc	
Collector-Emitter Sustaining Voltage (Note 1) (I _C = 100 mAdc, I _B = 0, V _{BE} = 1.5 Vdc)	BDX33B/BDX34B BDX33C/BDX34C	V _{CEX(sus)}	80 100	- -	Vdc	
Collector Cutoff Current $(V_{CE} = 1/2 \text{ rated } V_{CEO}, I_B = 0)$	T _C = 25°C T _C = 100°C	I _{CEO}	- -	0.5 10	mAdc	
Collector Cutoff Current $(V_{CB} = \text{rated } V_{CBO}, I_E = 0)$	T _C = 25°C T _C = 100°C	I _{CBO}	- -	1.0 5.0	mAdc	
Emitter Cutoff Current (V _{BE} = 5.0 Vdc, I _C = 0)		I _{EBO}	_	10	mAdc	
ON CHARACTERISTICS						
DC Current Gain (Note 1) (I _C = 3.0 Adc, V _{CE} = 3.0 Vdc)	BDX33B, 33C/34B, 34C	h _{FE}	750	_	-	
Collector-Emitter Saturation Voltage (I _C = 3.0 Adc, I _B = 6.0 mAdc)	BDX33B, 33C/34B, 34C	V _{CE(sat)}	_	2.5	Vdc	
Base-Emitter On Voltage (I _C = 3.0 Adc, V _{CE} = 3.0 Vdc)	BDX33B, 33C/34B, 34C	V _{BE(on)}	_	2.5	Vdc	
Diode Forward Voltage (I _C = 8.0 Adc)		V _F	_	4.0	Vdc	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 1. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

^{2.} Pulse Test non repetitive: Pulse Width = 0.25 seconds.

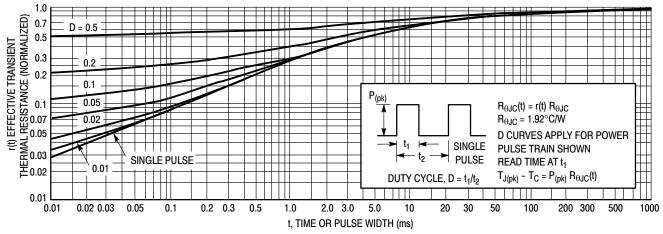


Figure 1. Thermal Response

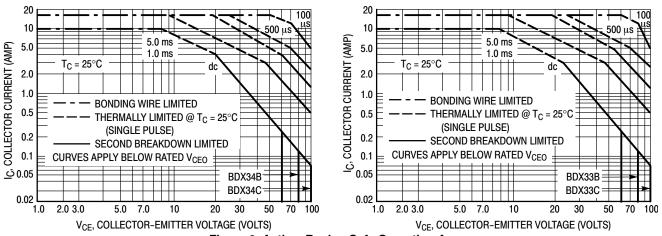
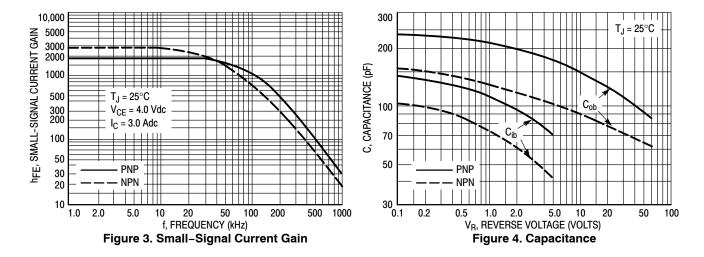


Figure 2. Active-Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation, i.e., the transistor must not be subjected to greater dissipation than the curves indicate. The data of Figure 3 is based on

 $T_{J(pk)} = 150^{\circ}\text{C}$; T_{C} is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} = 150^{\circ}\text{C}$. $T_{J(pk)}$ may be calculated from the data in Figure 4. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.



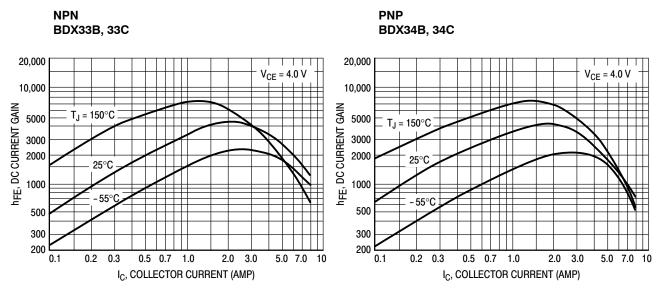


Figure 5. DC Current Gain

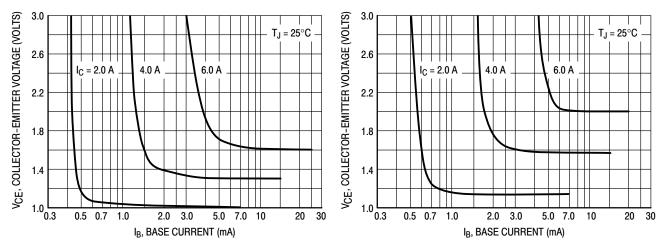


Figure 6. Collector Saturation Region

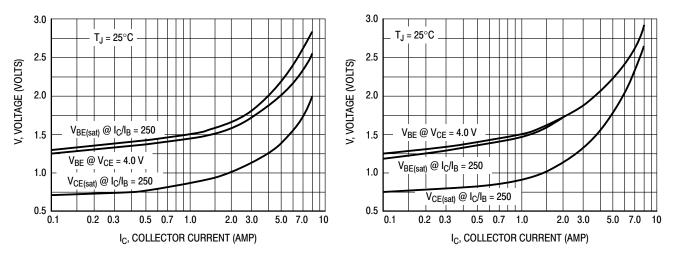


Figure 7. "On" Voltages

ORDERING INFORMATION

Device	Package	Shipping [†]
BDX33BG	TO-220 (Pb-Free)	50 Units / Rail
BDX33CG	TO-220 (Pb-Free)	50 Units / Rail

DISCONTINUED (Note NO TAG)

BDX34BG	TO-220 (Pb-Free)	50 Units / Rail
BDX34CG	TO-220 (Pb-Free)	50 Units / Rail

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

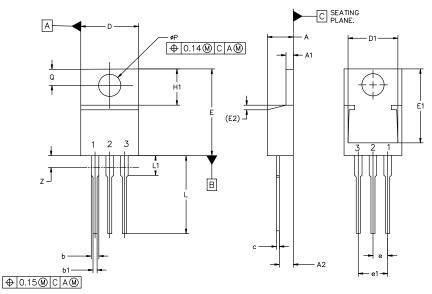
^{3.} **DISCONTINUED:** These devices are not recommended for new design. Please contact your **onsemi** representative for information. The most current information on these devices may be available on www.onsemi.com.





TO-220-3 10.10x15.12x4.45, 2.54P CASE 221A **ISSUE AL**

DATE 05 FEB 2025



MILLIMETERS					
DIM	MIN	NOM	MAX		
Α	4.07	4.45	4.83		
A1	1.15	1.28	1.41		
A2	2.04	2.42	2.79		
b	1.15	1.34	1.52		
b1	0.64	0.80	0.96		
С	0.36	0.49	0.61		
D	9.66	10.10	10.53		
D1	8.43	8.63	8.83		
Е	14.48	15.12	15.75		
E1	12.58	12.78	12.98		
E2	1.27 REF				

MILLIMETERS					
DIM	MIN	NOM	MAX		
е	2.42	2.54	2.66		
e1	4.83	5.08	5.33		
H1	5.97	6.22	6.47		
L	12.70	13.49	14.27		
L1	2.80	3.45	4.10		
Q	2.54	2.79	3.04		
ØΡ	3.60	3.85	4.09		
Z	-,	-,	3.48		

NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.

 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

STYLE 1:		STYLE 2:		STYLE 3:		STYLE 4:	
PIN 1.	BASE	PIN 1.	BASE	PIN 1.	CATHODE	PIN 1.	MAIN TERMINAL 1
2.	COLLECTOR	2.	EMITTER	2.	ANODE	2.	MAIN TERMINAL 2
3.	EMITTER	3.	COLLECTOR	3.	GATE	3.	GATE
4.	COLLECTOR	4.	EMITTER	4.	ANODE	4.	MAIN TERMINAL 2
STYLE 5:		STYLE 6:		STYLE 7:		STYLE 8:	
PIN 1.	GATE	PIN 1.	ANODE	PIN 1.	CATHODE	PIN 1.	CATHODE
2.	DRAIN	2.	CATHODE	2.	ANODE	2.	ANODE
3.	SOURCE	3.	ANODE	3.	CATHODE	3.	EXTERNAL TRIP/DELAY
4.	DRAIN	4.	CATHODE	4.	ANODE	4.	ANODE
STYLE 9:		STYLE 10:		STYLE 11:	:	STYLE 12:	:
PIN 1.	GATE	PIN 1.	GATE	PIN 1.	DRAIN	PIN 1.	MAIN TERMINAL 1
2.	COLLECTOR	2.	SOURCE	2.	SOURCE	2.	MAIN TERMINAL 2
3.	EMITTER	3.	DRAIN	3.	GATE	3.	GATE
4.	COLLECTOR	4.	SOURCE	4.	SOURCE	4.	NOT CONNECTED

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DESCRIPTION:	TO-220-3 10.10x15.12x4.45, 2.54P		PAGE 1 OF 1	

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